1		2	3	4		5	6	
HARTING	DI	N power fema	le connector	RoHS	: <b>AL</b> us	In addition to the hot-air-le to their different properties	ration of plated through holes for press evel (HAL), other PCB surfaces are getting more imp s - such as mechanical strength and coefficient of t configuration of PCB through holes.	oortant.
General information		2				]	drilled hole Ø	

General information		drilled hole Ø
Design	IEC 60603-2 types: D, E female	
No. of contacts	max. 48	
Contact spacing	5,08 mm	
Test voltage	1550V	
Contact resistance	max. 15mOhm	
Insulation resistance	min. 10º20hm	
Working current	6 A at 20°C (see derating diagram)	
3 Temperature range	−55°C +125°C	
	-40°C +105°C for press-in connectors (due to limit ations of PCB-material)	finished hole Ø
Termination technology	solder pins, solder lugs, wirewrap, press-in	
Clearance	min. 3,0 mm	
Сгеераде	min. 3,0 mm	
Insertion and withdrawal force	32pole max. 50N	
	48pole max. 75N	
Mating system	- PL 1 acc. to IEC 60 603-2 => 500 mating cycles	
Mating cycles	- PL 2 acc. to IEC 60 603-2 => 400 mating cycles	
	- PL 3 acc. to IEC 60 603-2 => 50 mating cycles	
UL file	E102079	
RoHS – compliant	Yes	
- Leadfree	Yes	
Hot plugging	No	—
		Assembly instructions
Insulator material		It is highly accommanded to use HADTING proces in table to ensure a
		It is highly recommended to use HARTING press-in tools to ensure a machines and further information about the press-in process.
Material	PBT (thermoplastics, glass fiber reinforcement 30%)	
Color	RAL 7032 (grey)	Soldering instructions
UL classification	UL 94-V0	
Material group acc. IEC 60664-1	IIIa (175 <u>&lt;</u> CTI < 400)	The connectors should be protected when being soldered in a dip, flow o
NFF classification	I3, F4	result of soldering operations or deformed as a result of overheating.
		=
		(1) For prototypes and short runs protect the connectors with an indust Cover the underside of the connector moulding and the adjacent parts o
D Contact material		heat and gases of the soldering apparatus from damaging the connector
Contact material	Copper alloy	<ul> <li>(2) For large series a jig is recommended. Its protective cover with a fast heat generated by the soldering apparatus. As an additional protection</li> </ul>
Plating termination zone	Sn over Ni for solder pins & lugs Ni for wirewrap & press-in	
Plating contact zone	Au over PdNi over Ni press-in: Au over Ni	
		Cross section of solder pins
╡		
Derating diagram acc. to IEC 60512-5	(Current carrying capacity)	0,27 mm <sup>2</sup>
The current carrying capacity is limite	d by maximum temperature A	
of materials for inserts and contacts	including terminals. 6	
The current capacity curve is valid fo	r continuous, non _ 5	0,53±0.05
E   interrupted current loaded contacts o	f connectors when	
simultaneous power on all contacts is the maximum temperature.	given, without exceeding	0
'	given, without exceeding	2
Control and test procedures according		
	.≝ ~             N.	
-		All Dimensions in mm Scale Free size tol.

3

2

0 20

40

60

80

Temperature [°C]

4

100

120 °C



Lross section of solde	er pins				
0,27 mm <sup>2</sup>	0,8±0,03				
	ensions in mm Size DIN A3	Scale 1:1	Free	size tol.	
HARTING	reserved	Created by STORCK		Inspec LEHNE	rted by RT
	PD - DE	Title DIN	<sup>itle</sup> DIN power fema		
HARTING Electronics GmbH D-32339 Espelkamp		<sup>Type</sup> DS	DS		904
5		6			

	7			8		
						7
termina	tion					
Dua	i	D-:!!		1 41		A
. Due I -		Drill			5±0,025 mm	$ ^{}$
	Tin plated PCB (HAL) acc. to EN 60352-5		Cu	-	nin. 25 μm	
	act. 10 EM 00002-0	-1-+	Sn 🦷		max. 15 µm	
			plated hole Ø Drilled hole Ø		4 – 1,09 mm	
		DFILL	Cu		5±0,025 mm	
	Chemical tin plated PCB		Sn		nin. 25 μm	
			sn plated hole Ø		nin. 0,8µm 0 — 1,10 mm	
		<u>`</u>	ed hole Ø	_		
		DFill			5±0,025 mm	
	Gold /Nickel		Cu Ni		nin. 25 μm 3 - 7 μm	В
	plated PCB					
		-1-4			5 – 0,12 µm	
			ed hole Ø		0 – 1,10 mm	
		Drill	ed hole Ø		5±0,025 mm	
	Silver plated		Cu	-	nin. 25 μm	
PCB Copper plated PCB (OSP)			Ag	_	1 – 0,3 µm	$\square$
			ed hole Ø		0 – 1,10 mm	
		Drill	ed hole Ø		5±0,025 mm	
			Cu	_	nin. 25 μm	
		plat	ed hole Ø	1,00	0 – 1,10 mm	
						C
	• • • •					
	-	o Diana		antalaa		
e a reli	able press-in proces	s. Please	e reter to the	caralog	UE FOF FOOLS,	
				-	<b>`</b>	
	· · · · · ·					
ow or ti ng.	ilm soldering baths. O	therwise,	tney might be	come cor	itaminated as a	
2	adhasiwa tana la T	acaband	1221 June too-			
ts of th	adhesive tape, e.g. T ne pcb as well as the	open sid	es of the conn		his will prevent	D
ctor. At	bout 140 + 5 mm of th	ne tape s	should suffice.			
ı fast a	iction mechanical locki	ng device	shields the co	onnectors	s from gas and	
ion a fo	oil can be used for co	vering th	ie parts that s	hould no	it be soldered.	
	Cross section of wi	rewrap p	osts			
	1					
					E	
		Ref.				┪_┤
		Sub.				
by Standardisation HOFFMANN		Date State				-
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